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Product Change Notification - JAON-04PFPM024

Date: 31 Aug 2016
Product Category: SMSC
Notification subject: CCB 2518 Final Notice: Qualification of CuPdAu bond wire in selected products of the 0.18 TSMC wafer technology available in 36L VQFN package at ANAC assembly site.
Notification text: **PCN Status:** Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18 TSMC wafer technology available in 36L VQFN package at ANAC assembly site.

Pre Change:

Palladium coated copper wire (PdCu) bond wire

Post Change:

Palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	ANAC assembly site	ANAC assembly site
Wire material	PdCu wire	CuPdAu wire
Die attach material	8290	8290
Molding compound material	G700	G700
Lead frame material	C194	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity and qualifying Palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated First Ship Date:

September 30, 2016 (date code: 1640)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	March 2016					->	August 2016					September 2016				
	09	10	11	12	13		32	33	34	35	36	37	38	39	40	
WW																
Initial PCN Issue Date		X														
Qual Report Availability												X				
Final PCN Issue Date												X				
Estimated Implementation Date															X	

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

March 10, 2016: Issued initial notification.

August 31, 2016: Issued final notification. Attached qualification report. Revised estimated first ship date from June 30, 2016 to September 30, 2016.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_JAON-04PFPM024_Qual_Report.pdf](#)
- [PCN_JAON-04PFPM024_Affected CPN.pdf](#)
- [PCN_JAON-04PFPM024_Affected CPN.xls](#)

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Affected Catalog Part Numbers (CPN)

PCN_JAON-04PFPM024
CATALOG_PART_NBR
LAN8700C-AEZG
LAN8700C-AEZG-AR2
LAN8700C-AEZG-TR
LAN8700C-AEZG-TR-A00
LAN8700C-AEZG-TR-AR1
LAN8700IC-AEZG
LAN8700IC-AEZG-CAG
LAN8700IC-AEZG-TR
LAN8700IC-AEZG-TR-CAG
USB3280-AEZG
USB3280-AEZG-TR